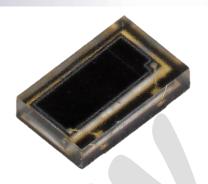


# SA3220P03CV00 Datasheet



**Broadband Silicon PIN Photodiode** 



### **Applications**

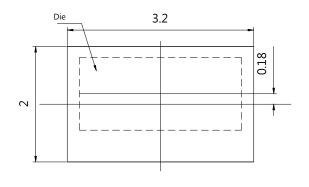
Health Monitoring (Heart Rate Monitoring, Pulse Oximetry)

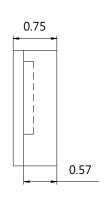
#### **Features**

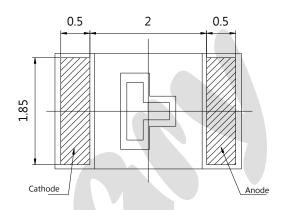
- Package: clear epoxy
- ESD: 2KV acc. to ANSI/ESDA/JEDEC JS-001 (HBM)
- Suitable for reflow soldering
- Especially suitable for applications from 400 nm to 1100 nm
- Small package (L x W x H): 3.2 mm x 2.0 mm x 0.75 mm (W x D x H)



## **Dimensional Drawing**







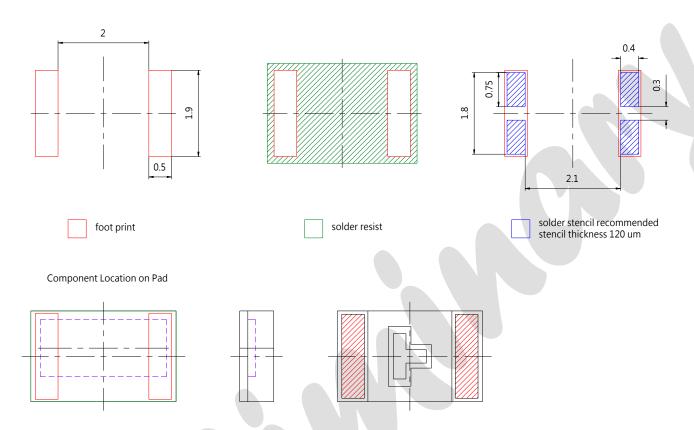
lead finish Au general tolerance ± 0.1



- 1. Dimensions are in millimeters.
- General tolerance is ± 0.1 mm. 2.



### **Recommended Solder Pad**





## **Maximum Ratings**

T<sub>A</sub>: 25 °C

Parameter	Symbol		Values
Operating temperature	T	Min.	-40 °C
	$T_{op}$	Max.	85 °C
Storage temperature	T	Min.	-40 °C
	$T_{ m stg}$	Max.	85 °C
Reverse voltage	$V_{R}$	Max.	16 V
ESD withstand voltage	17	Max.	214
acc. to ANSI/ESDA/JEDC JS-001 (HBM)	Vesd		2 kV



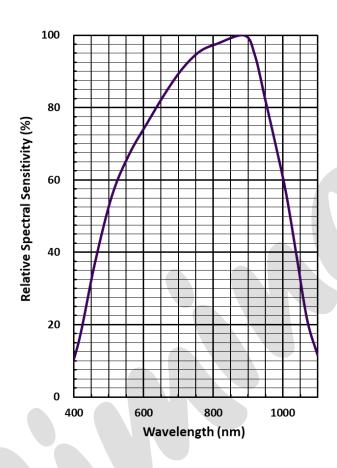
### **Characteristics**

T<sub>A</sub>: 25 °C

Parameter	Symbol		Values	
Wavelength of max sensitivity	λs max	Тур.	890 nm	
Spectral range of sensitivity	$\lambda_{10\%}$	Тур.	400 1100 nm	
Photocurrent	T_	Tun	1.1	
$E_e = 0.1 \text{ mW/cm}^2$ ; $\lambda = 530 \text{ nm}$ ; $V_R = 5 \text{ V}$	$I_P$	Тур.	1.1 μΑ	
Photocurrent	T.,	Tun	11 10	
$E_e = 1 \text{ mW/cm}^2$ ; $\lambda = 530 \text{ nm}$ ; $V_R = 5 \text{ V}$	I <sub>P</sub>	Тур.	11.18 μΑ	
Photocurrent	T.,	Tun	16.11	
$E_e = 0.1 \text{ mW/cm}^2$ ; $\lambda = 660 \text{ nm}$ ; $V_R = 5 \text{ V}$	Ip	Тур.	1.6 μΑ	
Photocurrent	T	Tun	15.924	
$E_e = 1 \text{ mW/cm}^2$ ; $\lambda = 660 \text{ nm}$ ; $V_R = 5 \text{ V}$	I <sub>P</sub>	Тур.	15.82 μΑ	
Photocurrent		Tun	1 0 4	
$E_e = 0.1 \text{ mW/cm}^2$ ; $\lambda = 940 \text{ nm}$ ; $V_R = 5 \text{ V}$	Ip	Тур.	1.8 μΑ	
Photocurrent	$I_P$	Tun	10.26 uA	
$E_e = 1 \text{ mW/cm}^2$ ; $\lambda = 940 \text{ nm}$ ; $V_R = 5 \text{ V}$	TP.	Тур.	19.36 μΑ	
Radiant sensitive area	Α	Тур.	2.81 mm <sup>2</sup>	
Dimensions of chip area	LxW	Тур.	2.75 x 1.23	
Differisions of chip area			mm x mm	
Half angle	φ	Тур.	60°	
Dark current	I.	Тур.	0.3 nA	
V <sub>R</sub> = 5 V	$I_R$	Max.	5 nA	
Rise time	+	Tun	0.063 μs	
$V_R = 5 \text{ V}; R_L = 50 \Omega; \lambda = 530 \text{ nm}$	$t_{\mathrm{r}}$	Тур.		
Rise time	+	Tun	26.46	
$V_R = 5 \text{ V}; R_L = 50 \Omega; \lambda = 940 \text{ nm}$	t <sub>r</sub>	Тур.	3.6 µs	
Fall time	<b>+</b> -	Tun	0.07.00	
$V_R = 5 \text{ V}; R_L = 50 \Omega; \lambda = 530 \text{ nm}$	t <sub>f</sub>	Тур.	0.07 μs	
Fall time	4-	Tun	3.5 μs	
$V_R = 5 \text{ V}; R_L = 50 \Omega; \lambda = 940 \text{ nm}$	$t_{f}$	Тур.		
Forward voltage	17_	Tun	2.01 V	
I <sub>F</sub> = 10 mA; E = 0	$V_{\mathrm{F}}$	Тур.	2.91 V	
Capacitance	С	C Tura	15.7 pF	
V <sub>R</sub> = 5 V; f = 1 MHz; E = 0	<u>.                                    </u>	Тур.		

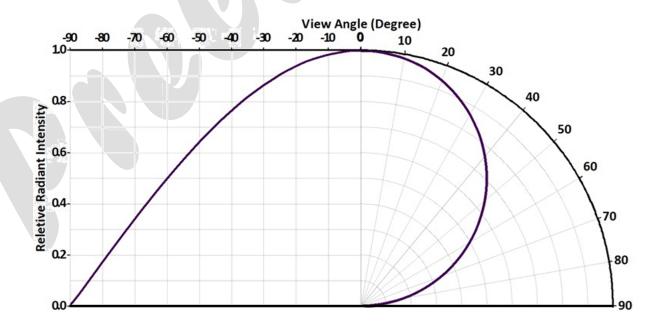
## **Relative Spectral Sensitivity**

 $S_{rel} = f(\lambda)$ 



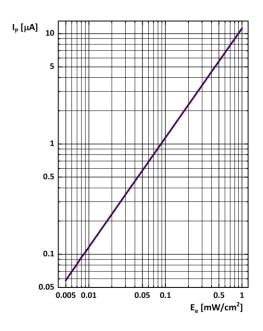
### **Directional Characteristics**

 $S_{rel} = f(\lambda)$ 



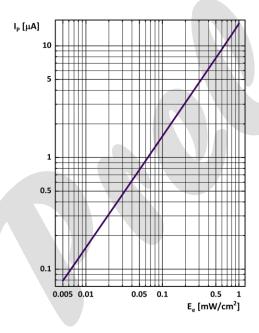
#### **Photocurrent**

#### $I_P = f(E_e); \lambda = 530 \text{ nm}; V_R = 5 \text{ V}$



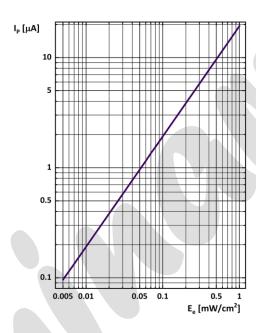
#### **Photocurrent**

$$I_P = f (E_e); \lambda = 660 \text{ nm}; V_R = 5 \text{ V}$$



#### **Photocurrent**

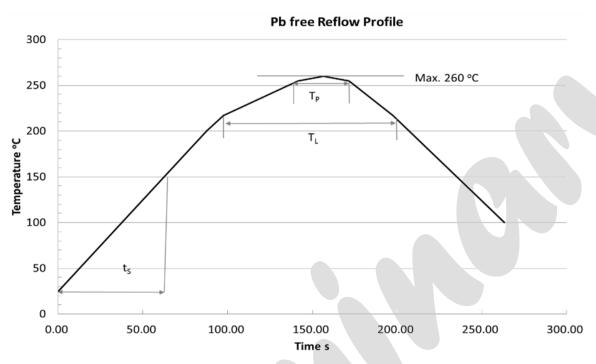
$$I_P = f(E_e); \lambda = 940 \text{ nm}; V_R = 5 \text{ V}$$





### **Reflow Soldering Profile**

Product complies to MSL Level 3 acc. to JEDEC J-STD-020E



Profile Feature	Symbol	l Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat			2	3	K/s
25 °C to 150 °C			۷	J	11/3
Time t <sub>S</sub>	ts	60	100	120	S
Tsmin to Tsmax	ıs	00	100	120	
Ramp-up rate to peak			2	3	K/s
T <sub>Smax</sub> to T <sub>P</sub>			2	J	11/3
Liquidus temperature	TL		217		°C
Time above liquidus temperature	$t_{L}$		80	100	S
Peak temperature	$T_P$		245	260	°C
Time within 5 °C of the specified	$T_P$	10	20	30	S
peak temperature TP - 5 K	IΡ	10	20	30	5
Ramp-down Rate			3	4	K/s
T <sub>P</sub> to 100 °C				4	11/3
Time				480	S
25 °C to T <sub>P</sub>					

- 1. Do not stress the silicone resin while it is exposed to high temperature.
- 2. The reflow process should not exceed 2 times.



#### **Disclaimer**

- Brightek reserves the right(s) on the adjustment of product material mix for the specification.
- The product meets Brightek published specification for a period of one year from date of shipment.
- The graphs shown in this datasheet are representing typical data only and do not show 3. guaranteed values.
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